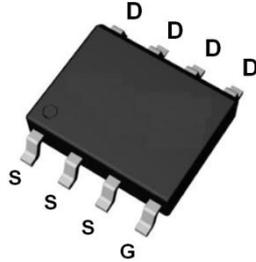
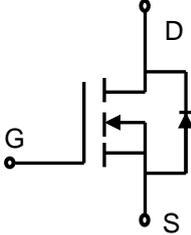


## Lonten N-channel 40V, 18A, 7.5mΩ Power MOSFET

|  |   |           |     |                             |       |       |     |
|--|---|-----------|-----|-----------------------------|-------|-------|-----|
| <p><b>Description</b><br/>                 These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.</p> <p><b>Features</b></p> <ul style="list-style-type: none"> <li>◆ 40V, 18A, <math>R_{DS(ON),max}=7.5m\Omega@V_{GS}=10V</math></li> <li>◆ Improved dv/dt capability</li> <li>◆ Fast switching</li> <li>◆ Green device available</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>◆ Motor Drives</li> <li>◆ UPS</li> <li>◆ DC-DC Converter</li> </ul> | <p><b>Product Summary</b></p> <table style="width: 100%; border: none;"> <tr> <td style="padding: 2px;"><math>V_{DSS}</math></td> <td style="padding: 2px;">40V</td> </tr> <tr> <td style="padding: 2px;"><math>R_{DS(on),max}@V_{GS}=10V</math></td> <td style="padding: 2px;">7.5mΩ</td> </tr> <tr> <td style="padding: 2px;"><math>I_D</math></td> <td style="padding: 2px;">18A</td> </tr> </table> <p><b>SOP-8 Pin Configuration</b></p> <div style="display: flex; justify-content: space-around; align-items: center;">   </div> <p style="text-align: center;">N-Channel MOSFET <span style="float: right;"></span></p> | $V_{DSS}$ | 40V | $R_{DS(on),max}@V_{GS}=10V$ | 7.5mΩ | $I_D$ | 18A |
| $V_{DSS}$  | 40V   |           |     |                             |       |       |     |
| $R_{DS(on),max}@V_{GS}=10V$  | 7.5mΩ   |           |     |                             |       |       |     |
| $I_D$  | 18A   |           |     |                             |       |       |     |

### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

| Parameter  | Symbol    | Value       | Unit             |
|--|-----------|-------------|------------------|
| Drain-Source Voltage                                   | $V_{DSS}$ | 40          | V                |
| Continuous drain current ( $T_A = 25^\circ\text{C}$ )  | $I_D$     | 18          | A                |
| Continuous drain current ( $T_A = 100^\circ\text{C}$ ) |           | 11.5        | A                |
| Pulsed drain current <sup>1)</sup>                     | $I_{DM}$  | 72          | A                |
| Gate-Source voltage                                    | $V_{GSS}$ | $\pm 20$    | V                |
| Power Dissipation ( $T_A = 25^\circ\text{C}$ )         | $P_D$     | 3.1         | W                |
| Storage Temperature Range                              | $T_{STG}$ | -55 to +150 | $^\circ\text{C}$ |
| Operating Junction Temperature Range                   | $T_J$     | -55 to +150 | $^\circ\text{C}$ |

### Thermal Characteristics

| Parameter                               | Symbol          | Value | Unit               |
|---|-----------------|-------|--------------------|
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 40    | $^\circ\text{C/W}$ |

**Package Marking and Ordering Information**

| Device    | Device Package | Marking   |
|-----------|----------------|-----------|
| LNL04R075 | SOP-8          | LNL04R075 |

**Electrical Characteristics**
 $T_J = 25^\circ\text{C}$  unless otherwise noted

| Parameter   | Symbol       | Test Condition   | Min. | Typ. | Max. | Unit             |
|---|--------------|--|------|------|------|------------------|
| <b>Static characteristics</b>                                 |              |  |      |      |      |                  |
| Drain-source breakdown voltage                                | $BV_{DSS}$   | $V_{GS}=0\text{ V}, I_D=250\mu\text{A}$                                | 40   | ---  | ---  | V                |
| Gate threshold voltage  | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$                                    | 1.0  | 1.5  | 2.0  | V                |
| Drain-source leakage current                                  | $I_{DSS}$    | $V_{DS}=40\text{ V}, V_{GS}=0\text{ V}, T_J = 25^\circ\text{C}$        | ---  | ---  | 1    | $\mu\text{A}$    |
|   |              | $V_{DS}=32\text{ V}, V_{GS}=0\text{ V}, T_J = 125^\circ\text{C}$       | ---  | ---  | 10   | $\mu\text{A}$    |
| Gate leakage current, Forward                                 | $I_{GSSF}$   | $V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$                                | ---  | ---  | 100  | nA               |
| Gate leakage current, Reverse                                 | $I_{GSSR}$   | $V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$                               | ---  | ---  | -100 | nA               |
| Drain-source on-state resistance                              | $R_{DS(on)}$ | $V_{GS}=10\text{ V}, I_D=10\text{ A}$                                  | ---  | 6.0  | 7.5  | $\text{m}\Omega$ |
|   |              | $V_{GS}=4.5\text{ V}, I_D=8\text{ A}$                                  | ---  | 7.5  | 9.5  | $\text{m}\Omega$ |
| Forward transconductance                                      | $g_{fs}$     | $V_{DS} = 5\text{ V}, I_D=10\text{ A}$                                 | ---  | 35   | ---  | S                |
| <b>Dynamic characteristics</b>                                |              |  |      |      |      |                  |
| Input capacitance   | $C_{iss}$    | $V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V},$<br>$F = 1\text{ MHz}$     | ---  | 2370 | ---  | pF               |
| Output capacitance  | $C_{oss}$    |  | ---  | 316  | ---  |                  |
| Reverse transfer capacitance                                  | $C_{riss}$   |  | ---  | 212  | ---  |                  |
| Turn-on delay time  | $t_{d(on)}$  | $V_{DD} = 20\text{ V}, V_{GS}=10\text{ V}, I_D = 9\text{ A}$           | ---  | 23.6 | ---  | ns               |
| Rise time   | $t_r$        |  | ---  | 98.8 | ---  |                  |
| Turn-off delay time   | $t_{d(off)}$ |  | ---  | 220  | ---  |                  |
| Fall time   | $t_f$        |  | ---  | 86.6 | ---  |                  |
| <b>Gate charge characteristics</b>                            |              |  |      |      |      |                  |
| Gate to source charge   | $Q_{gs}$     | $V_{DS}=20\text{ V}, I_D=10\text{ A},$<br>$V_{GS}= 10\text{ V}$        | ---  | 9.3  | ---  | nC               |
| Gate to drain charge  | $Q_{gd}$     |  | ---  | 6.8  | ---  |                  |
| Gate charge total   | $Q_g$        |  | ---  | 34.2 | ---  |                  |
| <b>Drain-Source diode characteristics and Maximum Ratings</b> |              |  |      |      |      |                  |
| Continuous Source Current                                     | $I_S$        |  | ---  | ---  | 18   | A                |
| Pulsed Source Current   | $I_{SM}$     |  | ---  | ---  | 72   | A                |
| Diode Forward Voltage <sup>2)</sup>                           | $V_{SD}$     | $V_{GS}=0\text{ V}, I_S=10\text{ A}, T_J=25^\circ\text{C}$             | ---  | ---  | 1.2  | V                |
| Reverse Recovery Time   | $t_{rr}$     | $I_S=9\text{ A}, di/dt=100\text{ A}/\mu\text{s}, T_J=25^\circ\text{C}$ | ---  | 24.2 | ---  | ns               |
| Reverse Recovery Charge                                       | $Q_{rr}$     |  | ---  | 12.3 | ---  | nC               |

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

 2: Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

**Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

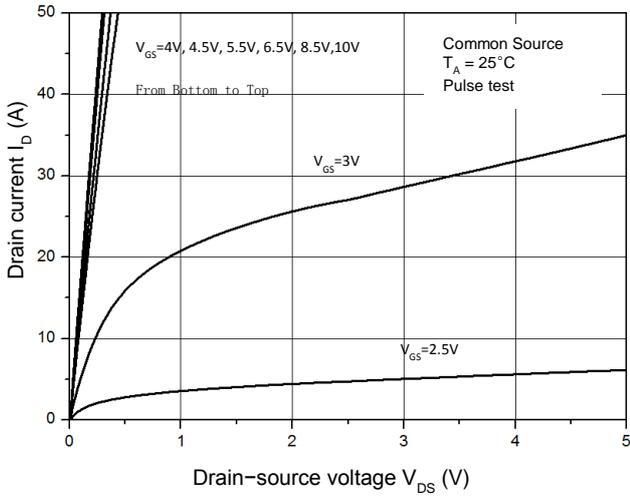


Figure 2. Transfer Characteristics

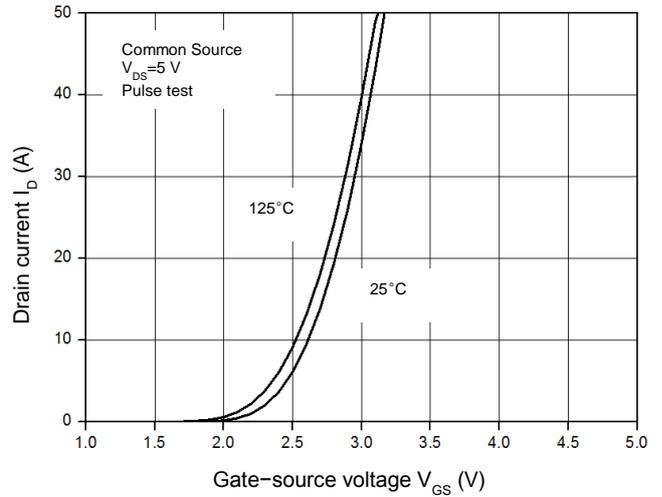


Figure 3. Capacitance Characteristics

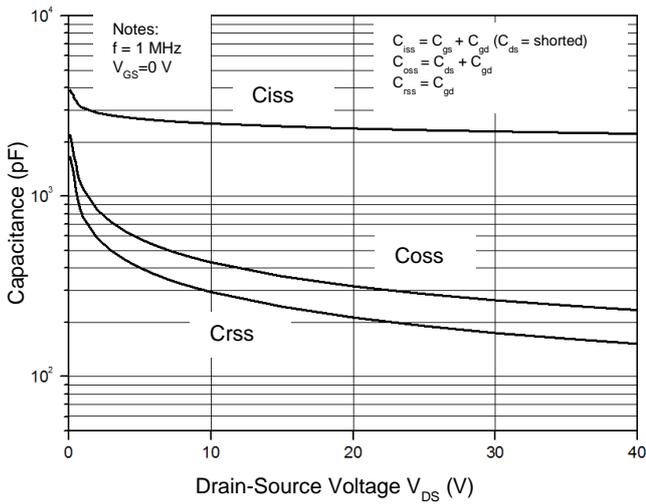


Figure 4. Gate Charge Waveform

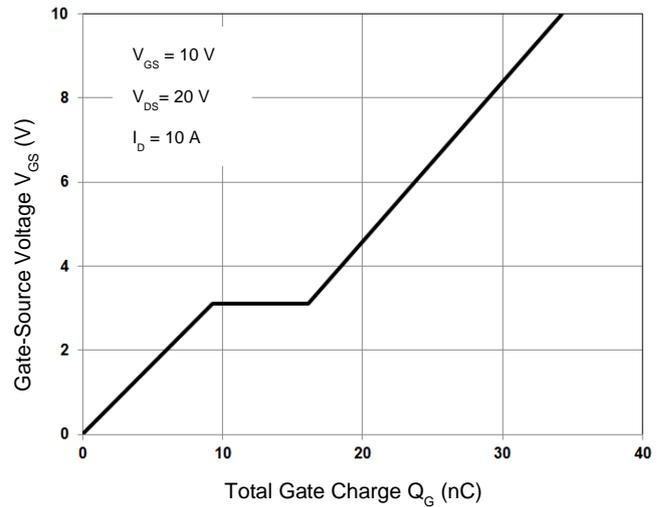


Figure 5. Body-Diode Characteristics

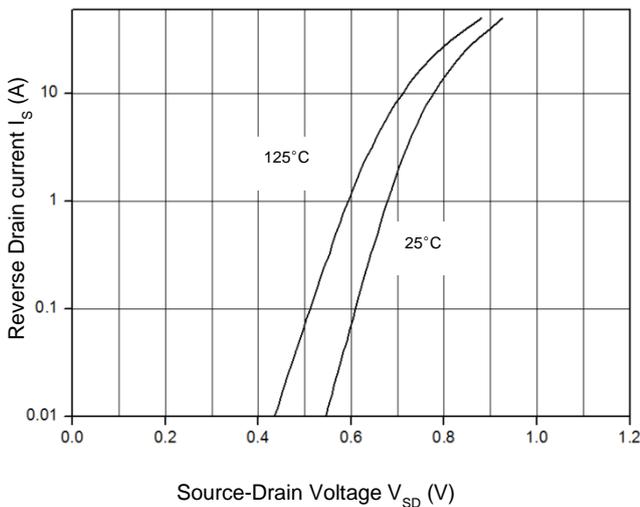


Figure 6. Rds(on)-Drain Current

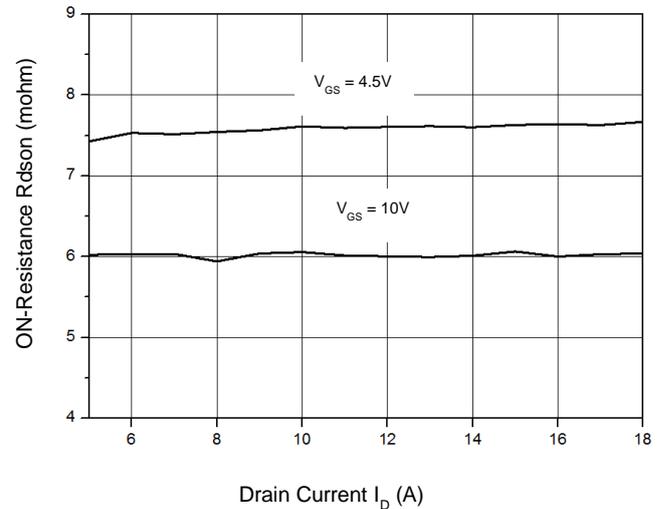


Figure 7. Rdson-Junction Temperature(°C)

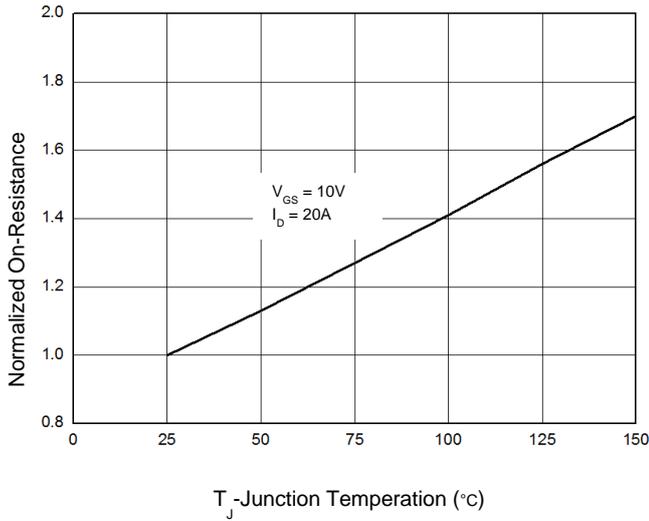


Figure 8. Maximum Safe Operating Area

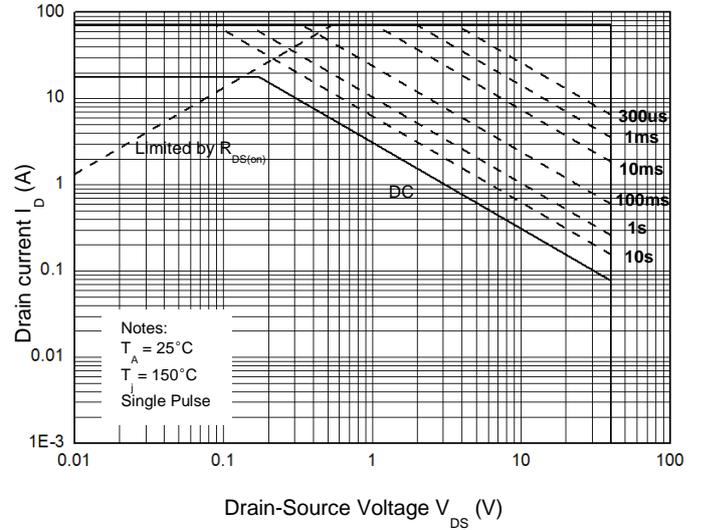
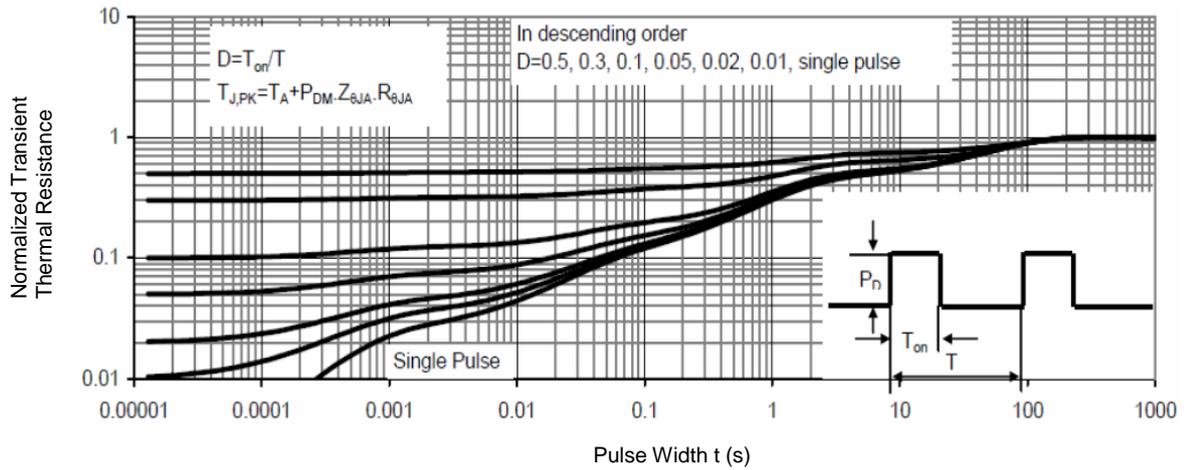


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJA)



**Test Circuit & Waveform**

Figure 8. Gate Charge Test Circuit & Waveform

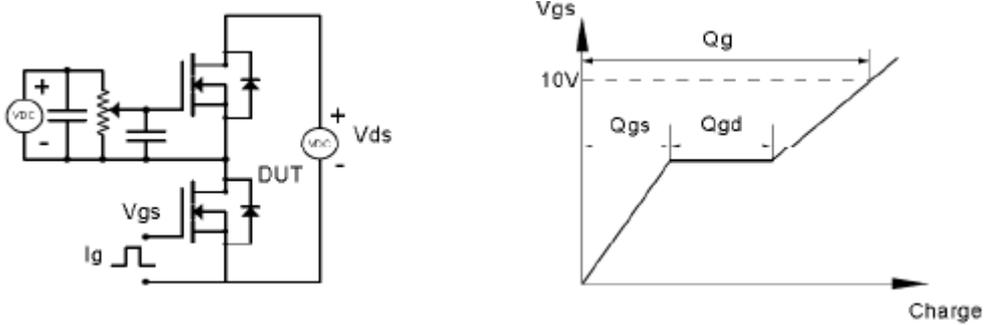


Figure 9. Resistive Switching Test Circuit & Waveforms

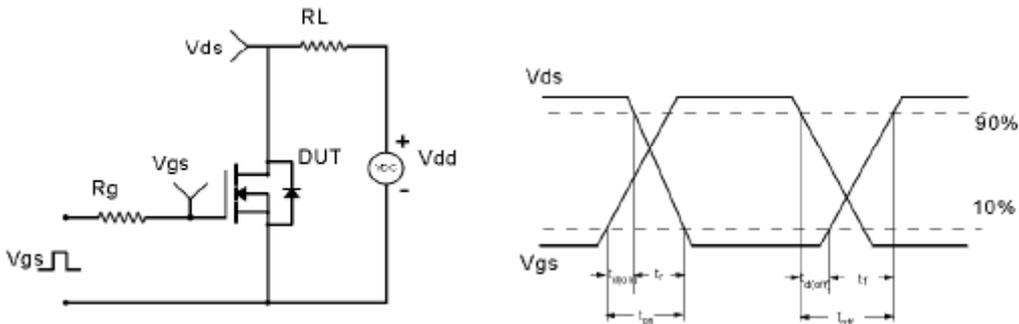


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

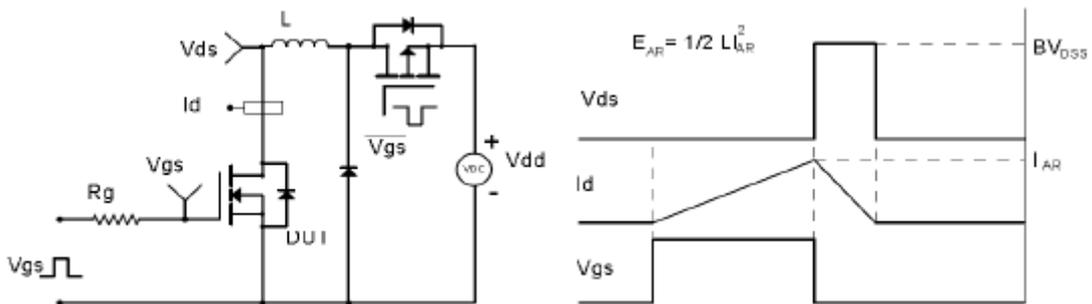
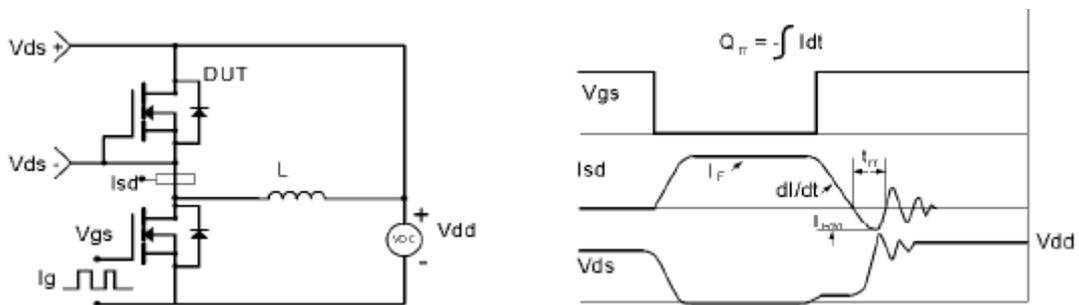
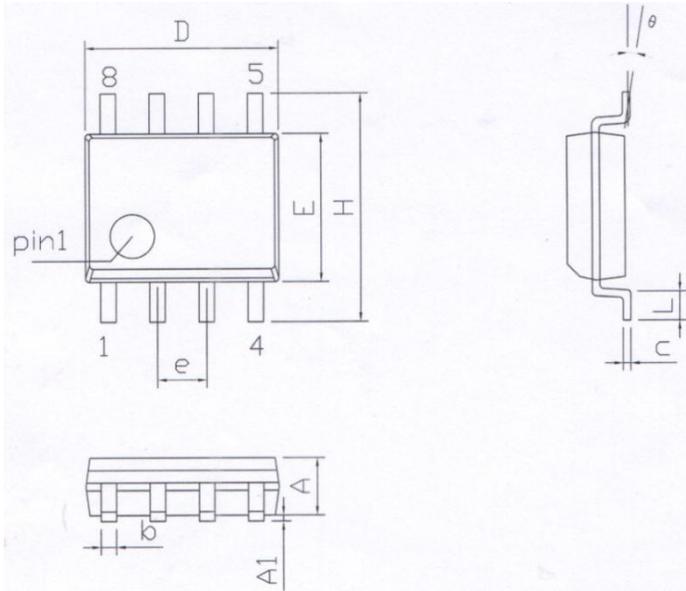


Figure 11. Diode Recovery Circuit & Waveform

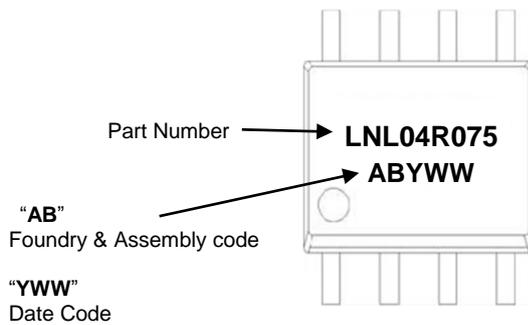


**Mechanical Dimensions for SOP-8**



| SYMBOL | COMMON DIMENSIONS |      |       |       |
|--------|-------------------|------|-------|-------|
|        | MILLIMETERS       |      | INCHS |       |
|        | MIN               | MAX  | MIN   | MAX   |
| A      | 1.35              | 1.65 | 0.053 | 0.065 |
| A1     | 0.10              | 0.25 | 0.004 | 0.010 |
| b      | 0.35              | 0.50 | 0.014 | 0.020 |
| c      | 0.19              | 0.27 | 0.007 | 0.011 |
| D      | 4.80              | 5.10 | 0.189 | 0.201 |
| E      | 3.80              | 4.10 | 0.150 | 0.161 |
| e      | 1.22              | 1.32 | 0.048 | 0.052 |
| H      | 5.80              | 6.20 | 0.228 | 0.244 |
| L      | 0.60              | 0.90 | 0.024 | 0.035 |
| θ      | 0°                | 8°   | 0°    | 8°    |

**SOP-8 Part Marking Information**



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